



Material Content Data Sheet



Sales Product Name	IDH05G65C5			Issued		29. August 2013		
MA#	MA000988686							
Package	PG-TO220-2-1			Weight*		1966.02 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	siliconcarbide	409-21-2	0.404	0.02		206	
	noble metal	gold	7440-57-5	0.031	0.00		16	
	non noble metal	tin	7440-31-5	0.008	0.00	0.02	4	226
leadframe	non noble metal	iron	7439-89-6	0.753	0.04		383	
	inorganic material	phosphorus	7723-14-0	0.226	0.01		115	
	non noble metal	copper	7440-50-8	751.797	38.24	38.29	382395	382894
wire	non noble metal	aluminium	7429-90-5	0.447	0.02	0.02	228	228
encapsulation	organic material	carbon black	1333-86-4	9.111	0.46		4634	
	plastics	epoxy resin	-	100.226	5.10		50979	
	inorganic material	silicondioxide	60676-86-0	498.095	25.34	30.90	253352	308965
leadfinish	non noble metal	tin	7440-31-5	14.487	0.74	0.74	7369	7369
plating	non noble metal	nickel	7440-02-0	0.198	0.01		101	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.01	1	101
heatspreader	inorganic material	phosphorus	7723-14-0	0.177	0.01		90	
	non noble metal	iron	7439-89-6	0.590	0.03		300	
	non noble metal	copper	7440-50-8	589.466	29.98	30.02	299827	300217
*deviation	< 10%	Sum in total:			100,00		1000000	

Important Remarks:

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